

 $\boldsymbol{m}\Omega$

Α

30

11.5

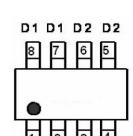
11.8

Features

- Dual N-Channel,5V Logic Level Control
- Enhancement mode
- Fast Switching
- High Effective

Application

- Power Management in Inverter System
- Synchronous Rectification



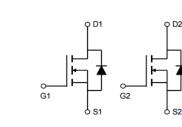
S1 G1 S2 G2

 V_{DSS}

 I_D

 $R_{DS(ON)\text{-}Max}$

Product Summary



top view



Absolute Maximum Ratings@Tj=25°C(unless otherwise specified)

Symbol	Parameter	Rating	Units
V _{DS}	Drain-Source Voltage	30	V
V_{GS}	Gate-Source Voltage	±20	V
I _D @T _A =25°C	Drain Current, V _{GS} @ 10V ³	11,8	Α
I _D @T _A =70°C	Drain Current, V _{GS} @ 10V ³	9.4	Α
I _{DM}	Pulsed Drain Current ¹	40	Α
P _D @T _A =25°C	Total Power Dissipation	2,5	W
T _{STG}	Storage Temperature Range	-55 to 150	$^{\circ}$
TJ	Operating Junction Temperature Range	-55 to 150	°C

Thermal Data

Symbol	Parameter	Value	Unit
Rthj-a	Maximum Thermal Resistance, Junction-ambient ³	50	°C/W



Electrical Characteristics@T_i=25°C(unless otherwise specified)

Symbol	Parameter	Test Conditions	Min.	Тур.	Max.	Units
BV _{DSS}	Drain-Source Breakdown Voltage	V _{GS} =0V, I _D =250uA	30	-	-	٧
R _{DS(ON)}	Static Drain-Source On-Resistance ²	V _{GS} =10V, I _D =11A	-	9.5	11.5	mΩ
		V _{GS} =4.5V, I _D =7A	-	13.8	18	mΩ
V _{GS(th)}	Gate Threshold Voltage	V _{DS} =V _{GS} , I _D =250uA	1	-	3	٧
g _{fs}	Forward Transconductance	V _{DS} =10V, I _D =11A	-	22	-	S
DSS	Drain-Source Leakage Current	V _{DS} =30V, V _{GS} =0V	-	-	10	uA
GSS	Gate-Source Leakage	V _{GS} = <u>+</u> 12V, V _{DS} =0V	-	-	<u>+</u> 100	nA
Qg	Total Gate Charge	I _D =11A	-	10,5	16.8	nC
Q _{gs}	Gate-Source Charge	V _{DS} =15V	-	2.5	-	nC
Q_{gd}	Gate-Drain ("Miller") Charge	V _{GS} =4.5V	-	6	-	nC
t _{d(on)}	Turn-on Delay Time	V _{DS} =15V	-	7	-	ns
t _r	Rise Time	I _D =1A	-	6	-	ns
t _{d(off)}	Turn-off Delay Time	R _G =3.3Ω,V _{GS} =10V	-	23	-	ns
t _f	Fall Time	R _D =15Ω	-	5	-	ns
C _{iss}	Input Capacitance	V _{GS} =0V	-	790	1280	pF
Coss	Output Capacitance	V _{DS} =25V	-	125	-	pF
C _{rss}	Reverse Transfer Capacitance	f=1.0MHz	-	105	-	pF
R_g	Gate Resistance	f=1,0MHz	-	2,1	-	Ω

Source-Drain Diode

Symbol	Parameter	Test Conditions	Min.	Тур.	Max.	Units
V_{SD}	Forward On Voltage ²	I _S =2.1A, V _{GS} =0V	1	-	1.2	٧
t _{rr}	Reverse Recovery Time	I _S =11A, V _{GS} =0V,	ı	22	-	ns
Q _{rr}	Reverse Recovery Charge	dl/dt=100A/µs	1	14	-	nC

Notes:

- 1.Pulse width limited by Max. junction temperature.
- 2.Pulse test
- 3.Surface mounted on 1 in² copper pad of FR4 board, t ≤10sec ; 125 °C/W when mounted on Min. copper pad.



Typical Characteristics

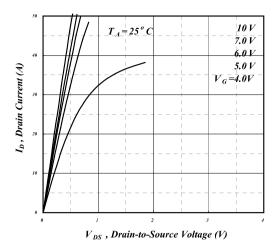


Fig 1. Typical Output Characteristics

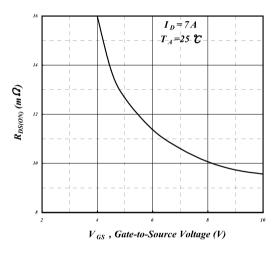


Fig 3. On-Resistance v.s. Gate Voltage

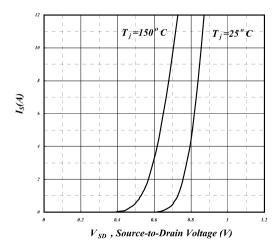


Fig 5. Forward Characteristic of Reverse Diode

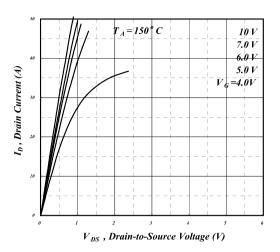


Fig 2. Typical Output Characteristics

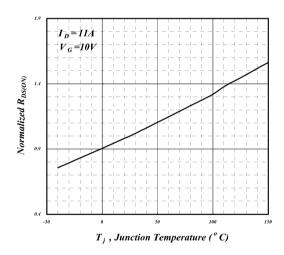


Fig 4. Normalized On-Resistance v.s. Junction Temperature

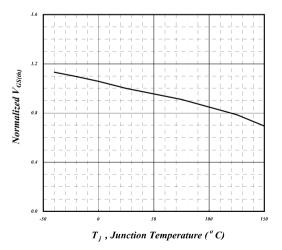


Fig 6. Gate Threshold Voltage v.s. Junction Temperature



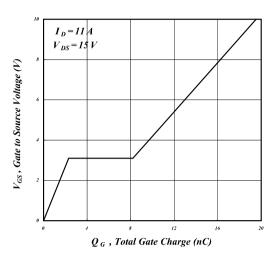


Fig 7. Gate Charge Characteristics

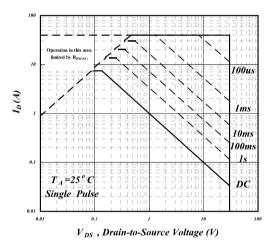


Fig 9. Maximum Safe Operating Area

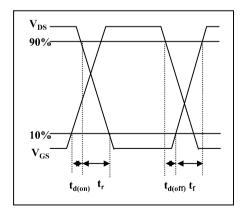


Fig 11. Switching Time Waveform

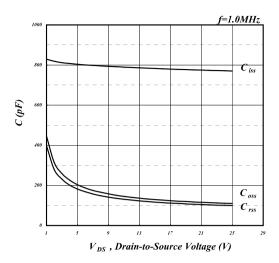


Fig 8. Typical Capacitance Characteristics

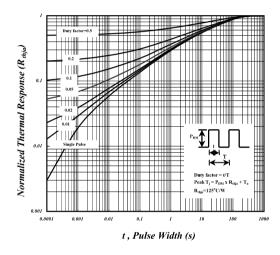


Fig 10. Effective Transient Thermal Impedance

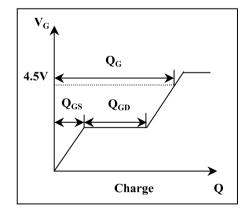


Fig 12. Gate Charge Waveform

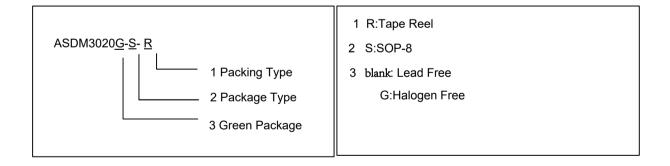


Ordering and Marking Information

Device	Marking	Package	Packing	Quantity
ASDM3020S	3020	SOP-8	Tape Reel	4000

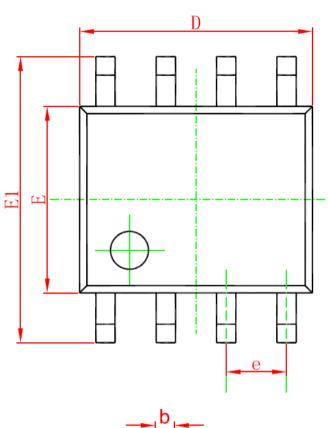
PACKAGE	MARKING
SOP-8	Lead Free Date Code
301 -0	Lot Number 3020 → Halogen Free □□□□ → Date Code

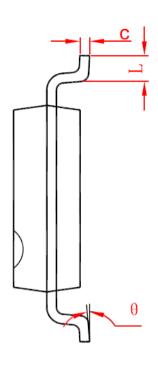
Ordering	Dealtone	
Lead Free	Halogen Free	Package
ASDM3020-S-R	ASDM3020G-S-R	SOP8

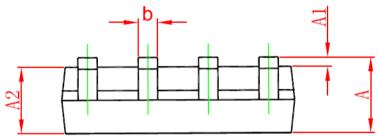




SOP-8 PACKAGE IN FORMATION







Ch l	Dimensions In Millimeters		Dimensions In Inches		
Symbol	Min	Max	Min	Max	
A	1. 350	1. 750	0. 053	0. 069	
A1	0. 100	0. 250	0.004	0. 010	
A2	1. 350	1. 550	0. 053	0. 061	
b	0. 330	0. 510	0. 013	0. 020	
С	0. 170	0. 250	0. 006	0. 010	
D	4. 700	5. 100	0. 185	0. 200	
Е	3. 800	4. 000	0. 150	0. 157	
E1	5. 800	6. 200	0. 228	0. 244	
е	1. 270	(BSC)	0. 050 (BSC)		
L	0. 400	1. 270	0. 016	0. 050	
θ	0°	8°	0°	8°	



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